AUTOMOTIVE GRADE

RoHS

HALOGEN

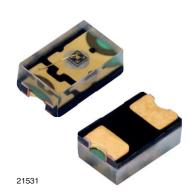
FREE

GREEN



Vishay Semiconductors

High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology



ADDITIONAL RESOURCES





DESCRIPTION

As part of the <u>SurfLightTM</u> portfolio, the VSMY1943X01 is an infrared, 940 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

FEATURES

- Package type: surface-mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- Operating temperature range: -40 °C to +105 °C
- Peak wavelength: λ_p = 940 nm
- Angle of half sensitivity: $\varphi = \pm 60^{\circ}$
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- · Miniature light barrier
- Photointerrupters
- Emitter source for proximity sensors

PRODUCT SUMMARY					
COMPONENT	I_e (mW/sr) at I_F = 50 mA	φ (°)	$\lambda_{\mathbf{p}}$ (nm)	t _r (ns)	
VSMY1943X01	6	± 60	940	5	

Note

· Test conditions see table "Basic Characteristics"

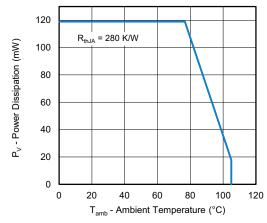
ORDERING INFORMAT	TION		
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY1943X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

· MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION SYMBOL		VALUE	UNIT	
Forward current		I _F	70	mA	
Peak forward current	$t_p/T = 0.5$, $t_p = 100 \mu s$	I _{FM}	140	mA	
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA	
Power dissipation		P _V	120	mW	
Junction temperature		T _j	110	°C	
Operating temperature range		T _{amb}	-40 to +105	°C	
Storage temperature range		T _{stg}	-40 to +110	°C	
Soldering temperature	According to Fig. 10, J-STD-020	T _{sd}	260	°C	
Thermal resistance junction-to-ambient	EIA / JESD 51	R _{thJA}	280	K/W	





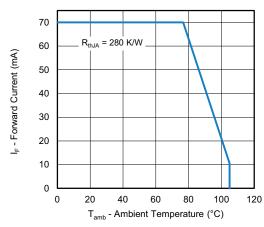


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 50 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.4	1.7	V
	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.5	=	V
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	V _F	-	2.5	-	V
Reverse current		I _R	Not designed for reverse operation			μΑ
Junction capacitance	$V_R = 0 \text{ V, } f = 1 \text{ MHz,}$ $E = 0 \text{ mW/cm}^2$	CJ	-	30	-	pF
Positional formación	$I_F = 50 \text{ mA}, t_p = 20 \text{ ms}$	le	4	6	8	mW/sr
Radiant intensity	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	l _e	-	80	-	mW/sr
Radiant power	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	фе	-	40	-	mW
Angle of half intensity		φ	-	± 60	-	0
Peak wavelength	I _F = 70 mA	λ_{p}	920	940	960	nm
Spectral bandwidth	I _F = 70 mA	Δλ	-	55	-	nm
Rise time	I _F = 70 mA, 10 % to 90 %	t _r	-	5	-	ns
Fall time	I _F = 70 mA, 10 % to 90 %	t _f	-	6	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

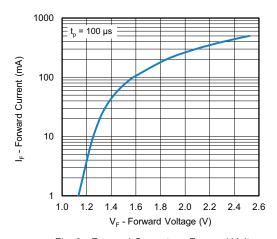


Fig. 3 - Forward Current vs. Forward Voltage

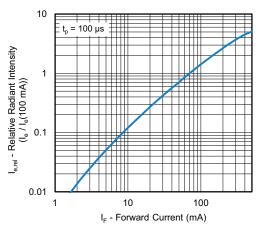


Fig. 4 - Relative Radiant Intensity vs. Ambient Temperature

300 Max. 260 °C 255 250 ≠245 °C 240 200 remperature (°C) Max. 30 s 150 120 s Max. 100 s 100 Max. ramp down 6 °C/s 50 Max. ramp up 3 °C/s 0 50 100 200 250 300 150 19841 Time (s)

REFLOW SOLDER PROFILE

Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

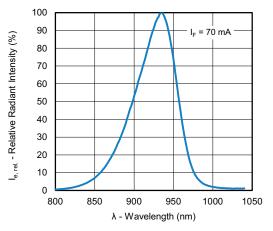


Fig. 5 - Relative Radiant Intensity vs. Wavelength

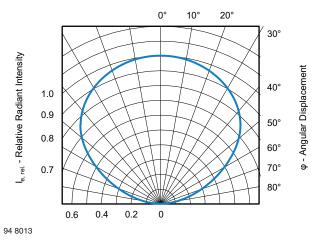


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

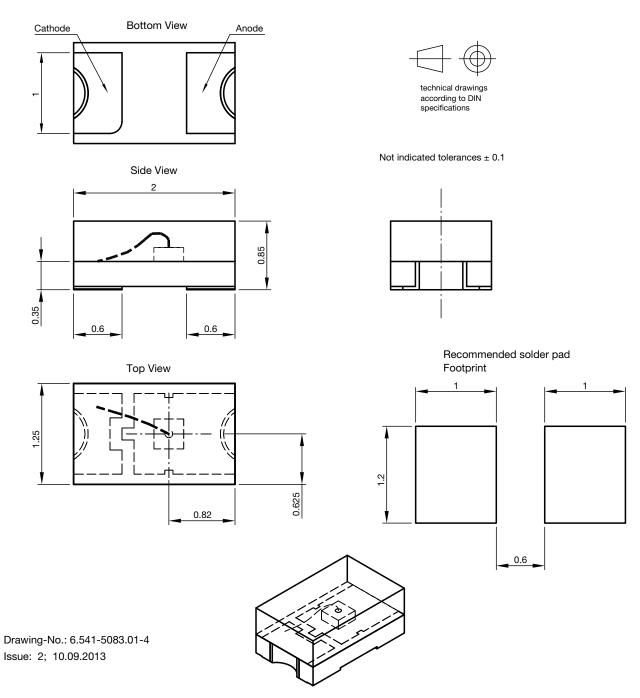
Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

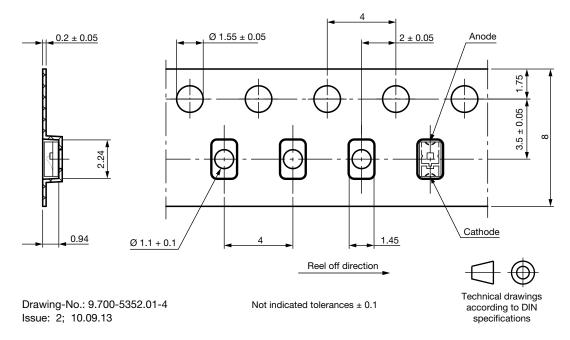
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



PACKAGE DIMENSIONS in millimeters

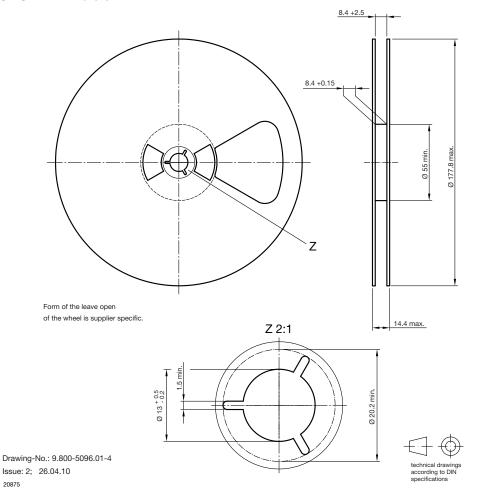


BLISTER TAPE DIMENSIONS in millimeters



REEL DIMENSIONS in millimeters

20875





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